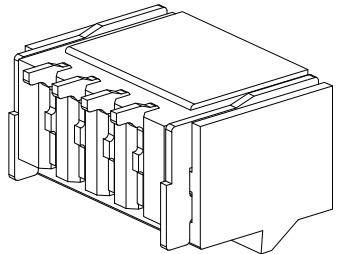
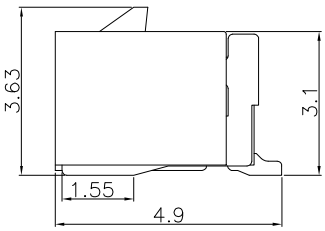
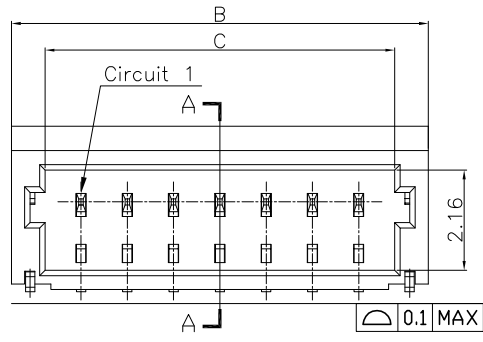


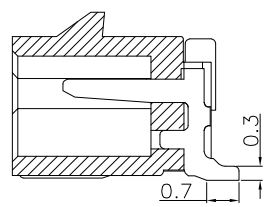
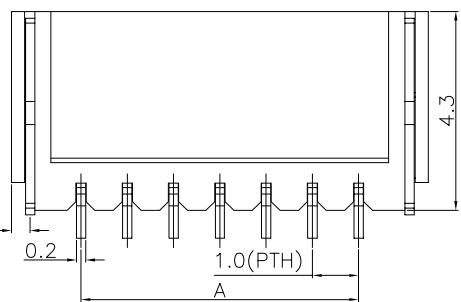
The product using material and processing must conform to the "WI-PZ-001"HSF technical standard control requirements

RoHS+HF

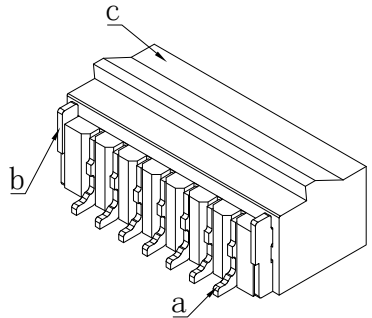


3D VIEW

- NOTE:
- 1.MATERIAL SPECIFICATION:
 - 1-1.CONTACT: PHOSPHOR BRONZE
 - 1-2.SOLDER TABS: PHOSPHOR BRONZE
 - 1-3.HOUSING: LCP UL94V-0
 - 2.PLATING SPECIFICATION:
 - 2-1.CONTACTS: BRIGHT TIN PLATED OVER ALL.
 - 2-2.SOLDER TABS: BRIGHT TIN PLATED OVER ALL.
 - 3.MECHANICAL PERFORMANCE:
 - 3-1.RETENTIVITY FORCE: 0.5KGF/pin min
 - 3-2.DURABILITY: 50 CYCLES.
 - 4.ELECTRICAL PERFORMANCE:
 - 4-1.CURRENT RATING: 1.0A
 - RATED VOLTAGE : 50V AC/DC
 - 4-2.CONTACT RESISTANCE: 20 mΩ MAX
 - 4-3.INSULATION RESISTANCE: 100MΩ Min
 - 4-4.DIELECTRIC WITHSTANDING : 500V
 - 5.ENVIRONMENTAL PERFORMANCE:
 - 5-1.OPERATING TEMPERATURE: -25°C~+105°C.
 - 6.PACKAGE SPEC:REEL/1500pcs
 - 7.P/N:



SECTION A-A



3D VIEW

△A1

SERIES NO: A1002 W 9 1-1 XX 2 X X 0

CONNECTOR: W-WAFER

ANGLE: 9-90°

TYPE: 1-TYPE 1

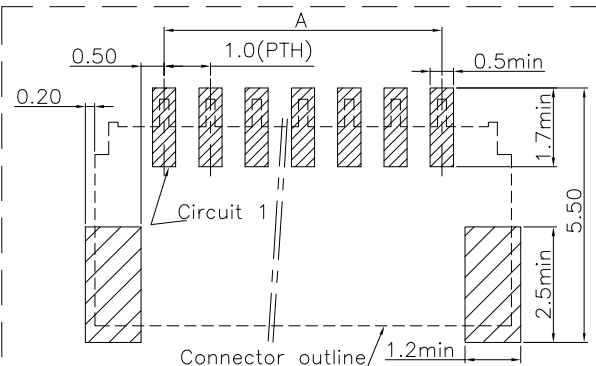
ROW NO: 1-SINGLE ROW

COLOR: A-BLACK S-NATURE

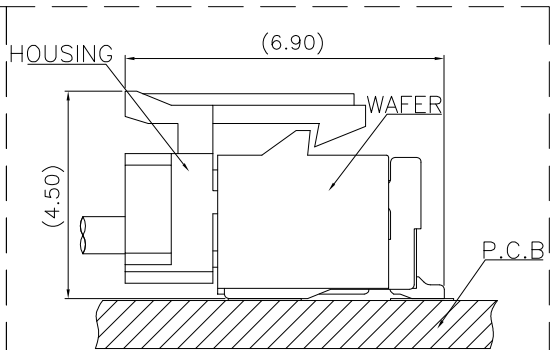
PLATING: A-ALL AU G/F C-BRIGHE TIN D-MATTE Tin

TERMIPOINT: 2-SMT

PIN Q'PY: 02~20



SMT SIDE ENTRY TYPE PCB LAYOUT



ASSEMBLY LAYOUT

Ordering Information & Dimensions

Circuit	Dimensions (mm)			Circuit	Dimensions (mm)		
	A	B	C		A	B	C
02	1.00	4.00	2.45	12	11.00	14.00	12.45
03	2.00	5.00	3.45	13	12.00	15.00	13.45
04	3.00	6.00	4.45	14	13.00	16.00	14.45
05	4.00	7.00	5.45	15	14.00	17.00	15.45
06	5.00	8.00	6.45	16	15.00	18.00	16.45
07	6.00	9.00	7.45	17	16.00	19.00	17.45
08	7.00	10.00	8.45	18	17.00	20.00	18.45
09	8.00	11.00	9.45	19	18.00	21.00	19.45
10	9.00	12.00	10.45	20	19.00	22.00	20.45
11	10.00	13.00	11.45				

REV.	REVISION RECORD	DATE		GENERAL TOLERANCES		SCALE: 1:1	NAME	DATE	PART.NO: A1002W91-1XX2XX0	DWG.NO: ENDE05	 WanLian Technology Co., Ltd	
A0	NEW RELEASE	21.11.17		LINEAR	ANGLES	APPROVED	Wang_jr	23.09.08				
A1	PART NUMBER RENEWAL	23.09.08		0.0±0.35	X°REF±6°	DESIGNER	H_Gao	23.09.08	TITLE: Pitch 1.00mm 90°SH 单排卧贴带锁扣 Wafer			
			UNIT:mm	0.00±0.25	X°±3°	DRAWN	LX_HOU	23.09.08				
			SIZE: A4	0.000±0.10	X°X' ±2°							

